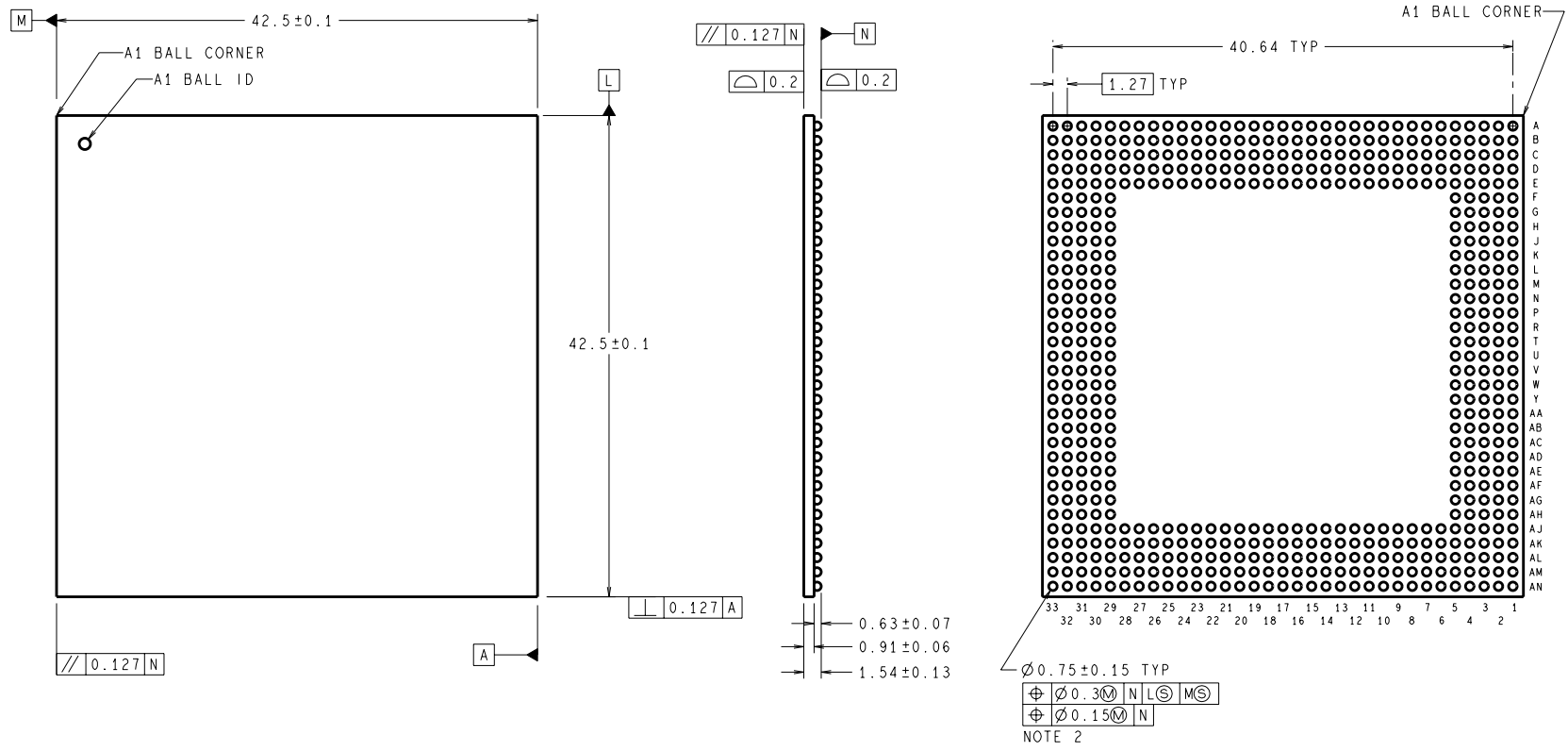


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11936	04/08/1998	TL/



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
2. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
3. REFERENCE JEDEC REGISTRATION MO-192, VARIATION BAV-1, DATED SEP 1996.
4. REFERENCE ANAM DRAWING 71290, DATED 02/01/1996.

APPROVALS		DATE		 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN T. LEQUANG		04/08/1998			
DFTG. CHK.				SBGA, 42.5 X 42.5 X 1.54mm, 560 BALL, 1.27mm PITCH	
ENGR. CHK.					
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
 INCH (MM)		N/A	C	(SC)MKT-UF0560A	A
DO NOT SCALE DRAWING				SHEET 1 of 1	